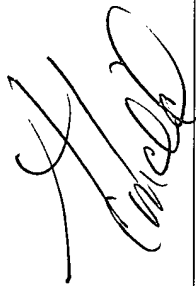
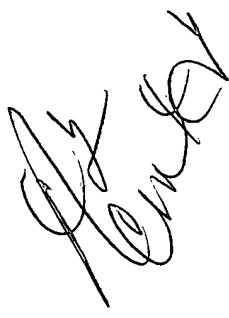


A. at least one woven fiber reinforcement material formed from at least one fiber free of basalt glass; and

 B. at least one matrix material in contact with at least a portion of the at least one reinforcement material, wherein the at least one matrix material is chosen from ceramics, glass ceramics, and macromolecules composed of long chains of atoms that are linked together and that can become entangled in solution or the solid state, the at least one matrix material comprising at least one non-fluorinated polymer and at least one inorganic filler, wherein the at least one inorganic filler comprises at least one non-hydratable, lamellar inorganic solid lubricant having a high electrical resistivity and wherein the at least one inorganic filler comprises at least 6 weight percent of a total combined weight of the at least one inorganic filler and the at least one matrix material on a total solids basis.

20. (Amended) An electronic support comprising:

A. at least one woven fiber reinforcement material; and

 B. at least one matrix material in contact with at least a portion of the at least one reinforcement material, wherein the at least one matrix material is chosen from ceramics, glass ceramics, and macromolecules composed of long chains of atoms that are linked together and that can become entangled in solution or the solid state, the at least one matrix material comprising at least one non-fluorinated polymer and at least one inorganic filler, wherein the at least one inorganic filler comprises at least one non-hydratable, lamellar inorganic solid lubricant having a high electrical resistivity and wherein the at least one inorganic filler comprises greater than 10 weight percent of a

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total combined weight of the at least one inorganic filler and the at least one matrix material on a total solids basis.

21. (Amended) An electronic support comprising:

- A. at least one woven fiber reinforcement material formed from at least one fiber free of basalt glass; and
- B. at least one matrix material in contact with at least a portion of the at least one reinforcement material, wherein the at least one matrix material is chosen from ceramics, glass ceramics, and macromolecules composed of long chains of atoms that are linked together and that can become entangled in solution or the solid state, the at least one matrix material comprising at least one non-fluorinated polymer and at least one inorganic filler, wherein the at least one inorganic filler comprises at least one inorganic filler having a thermal conductivity of at least 30 W/mK and a high electrical resistivity and wherein the at least one inorganic filler comprises at least 6 weight percent of a total combined weight of the at least one inorganic filler and the at least one matrix material on a total solids basis.

28. (Amended) An electronic support comprising:

- A. at least one woven fiber reinforcement material; and
- B. at least one matrix material in contact with at least a portion of the at least one reinforcement material, wherein the at least one matrix material is chosen from ceramics, glass ceramics, and macromolecules composed of long chains of atoms that are linked together and that can become entangled in solution or the solid state, the at least one matrix material comprising at least one non-fluorinated polymer and at least one inorganic filler, wherein the at least one inorganic filler comprises at least one

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inorganic filler having a thermal conductivity of at least 30 W/mK and a high electrical resistivity and wherein the at least one inorganic filler comprises greater than 10 weight percent of a total combined weight of the at least one inorganic filler and the at least one matrix material on a total solids basis.

29. (Amended) An electronic support comprising:

A. at least one fiber reinforcement material; and

B. at least one matrix material in contact with at least a portion of the at least one woven fiber reinforcement material, wherein the at least one matrix material is chosen from ceramics, glass ceramics, and macromolecules composed of long chains of atoms that are linked together and that can become entangled in solution or the solid state, the matrix material comprising at least one inorganic filler in an amount sufficient to inhibit electrical shorts due to conductive anodic filament formation through a thickness of the electronic support.

39. The electronic support according to claim 30, wherein the at least one inorganic filler is an expansible clay mineral.

45. (Amended) An electronic support comprising:

A. at least one woven fiber reinforcement material; and

B. at least one matrix material in contact with at least a portion of the at least one woven fiber reinforcement material, wherein the at least one matrix material is chosen from ceramics, glass ceramics, and macromolecules composed of long chains of atoms that are linked together and that can become entangled in solution or the solid state, the matrix material comprising at least one inorganic filler selected from a material

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having a cation exchange capacity of at least 20 meq/100 g, an expansible clay mineral, and combinations thereof.

46. (Amended) A method of forming an electronic support, the method comprising:

- A. combining at least one inorganic filler with at least one solvent material;
- B. dispersing the at least one inorganic filler and the at least one solvent material in an at least one matrix material, wherein the at least one matrix material is chosen from ceramics, glass ceramics, and macromolecules composed of long chains of atoms that are linked together and that can become entangled in solution or the solid state;
- C. contacting the at least one matrix material comprising the at least one inorganic filler dispersed therein with at least one reinforcement material to form a prepreg layer; and
- D. at least partially setting the at least one matrix material of the prepreg layer.--

**REMARKS**

**I. Support for Amendments**

Support for the amendment to the title of the application may be found, *inter alia*, in the specification and claims of the presently claimed invention.

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